



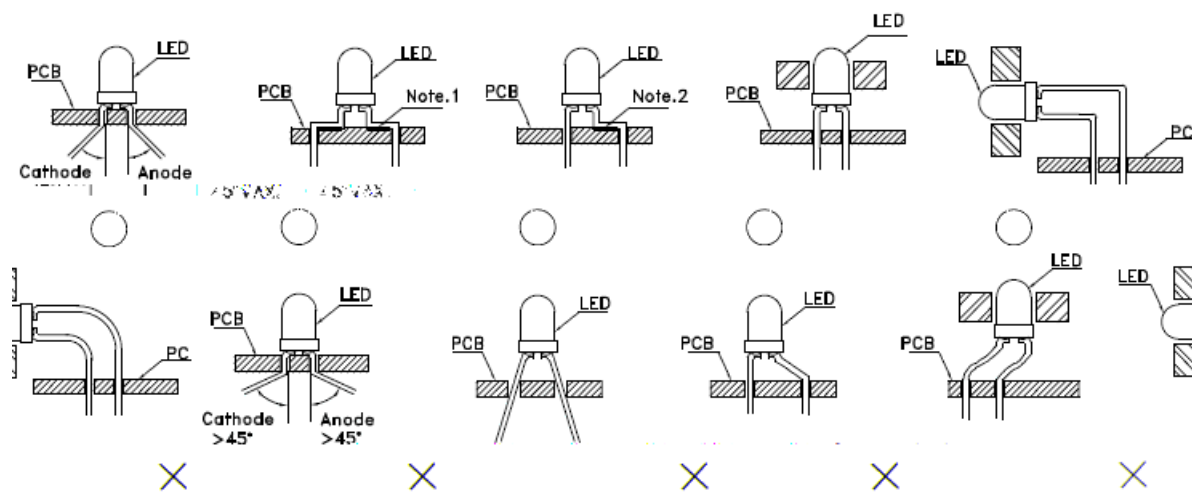




## PACKAGE

### LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.(Fig.1)



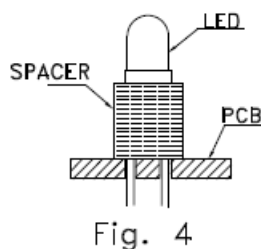
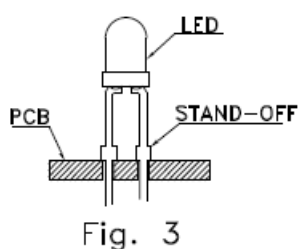
-2: Do not route PCB

Trace in the contact area between the lead frame and the PCB to prevent short-circuit.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2)



3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.





**LIGHT**



## Infrared Emitting Diode Specification

●Commodity: Infrared emitting diode

●Intensity Bin Limits (At 50mA)

| BIN CODE | Min.(mW/sr) | Max.(mW/sr) |
|----------|-------------|-------------|
| 27       | 10.5        | 14          |
| 28       | 14          | 18.5        |